



PRODUCT DATASHEET



DC Input Photo Coupler

- DIP4 Gullwing 400mil
- Zero-Cross TRIAC

TD308X-4L(M)-GV





APPLICATIONS:

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

TD308X-4L(M) Series

DESCRIPTION:



The TDTD308X-4L(M) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo TRIAC in a plastic DIP4 package with Gullwing lead forming option.

With the robust coplanar double mold structure, TD308X-4L(M) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with zero-cross photo TRIAC output
- Operating temperature range -40°C to +100°C
- REACH & RoHS compliance; Halogen free
- MSL class 1
- Regulatory Approvals:
 - o UL UL1577
 - o VDE EN60747-5-5 (VDE0884-5)
 - o CQC GB4943.1, GB8898
 - cUL CSA Component Acceptance Service Notice 5A



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NAMING & ORDERING INFORMATION:

Naming Information:

TD308 X - 4L (M) - G V				
TD308	Part Number			
×	Selection: LED Trigger Current (X=1~3)			
4L	DIP4 Based Package			
Μ	Lead Form Option: DIP4 Gullwing			
G	Green Option			
V	VDE Option			

Ordering Information:

TD308 <mark>X</mark> -4L(M)-GV						
	<u>X</u> = Selection: LED Trigger Current (X=1~3)					
Part Number	Symbol	Symbol Values			Max. Unit	Test Condition
	Symbol	Min. Typ. Max.	Max.			
TD3081-4L(M)-GV				15		L =100m A
TD3082-4L(M)-GV	IFT			10	mA	I _™ =100mA Terminal
TD3083-4L(M)-GV				5		Voltage=3V

Version No.	Original Release Date
Rev: A00	05/09/2024



Image: PIN Definition 1 Anode 2 Cathode 3 Terminal 4 Terminal

Schematic Diagram:

Marking Information: **Marking Definition** TD Manufacturer Code TD 308X Part Number & Rank 30XX V **VDE** Applicable VYAWW Y **Fiscal Year** А Manufacturing Code WW Work Week

Labelling Information:





Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit			
INPUT						
Forward Current	IF	60	mA			
Reverse Voltage	VR	6	V			
Junction Temperature	Tj	125	°C			
Input Power Dissipation	Pı	100	mW			
	OUTPUT					
Off-State Output Terminal Voltage	Vdrm	800	V			
Peak Repetitive Surge Current PW=100μs, 120pps	Ітѕм	1	А			
On-State RMS Current	It(rms)	100	mA			
Junction Temperature	Tj	125	°C			
Output Power Dissipation	Po	300	mW			
COMMON						
Total Power Dissipation	P _{tot}	400	mW			
Isolation Voltage	V _{iso}	5000 ^{*1}	Vrms			
Operating Temperature	T _{opr}	-40~+100	°C			
Storage Temperature	T _{stg}	-55~+125	°C			
Soldering Temperature	T _{sol}	260 ^{*2}	°C			

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

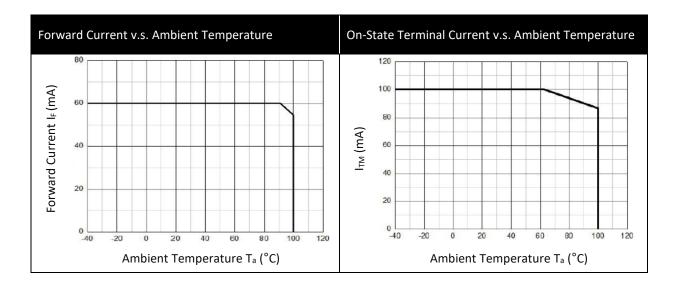
Electrical Op	otical Characteristics	at T _a =25°C:
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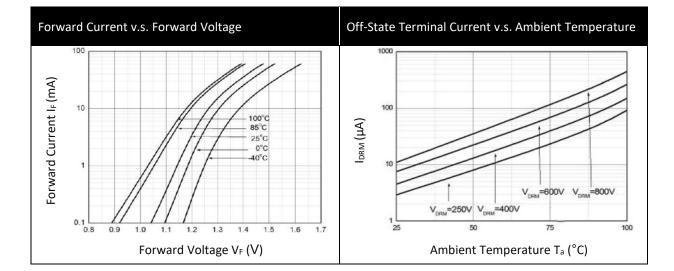
Paramete	er	Symbol	Min.	Values Typ.	Max.	Unit	Test Condition
	INPUT						
Forward Voltage		V _F		1.24	1.4	v	I _F =10mA
Reverse Current		I _R			10	μΑ	V _R =6V
Input Capacitance		CIN		8.5	250	pF	V=0, f=1kHz
		1	OUTPU	JT	I		
Peak Off-State Curre Either Direction	nt	Idrm			500 ^{*1}	nA	V_{DRM} =Rated V_{DRM} I _F =0
Peak Off-State Voltag	ge	V _{TM}		1.59	2.5	v	I _{TM} =100mA
	Critical Rate of Rise of Off-State		1000			V/µs	V _{PEAK} =400V I _F =0
		TRAN	NSFER CHAR	ACTERISTICS			
	TD3081-4L	IFT			15	mA	I™=100mA Terminal Voltage=3V
LED Trigger Current	TD3082-4L				10		
	TD3083-4L				5		
Holding Current		Ін		237		μA	
Isolation Resistance		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.4	1	pF	V=0, f=1MHz
ZERO-CROSSING CHARACTERISTICS							
Inhibit Voltage		VINH			20	V	IF=Rated IFT
Leakage in Inhibited State		I _{DRM2}			500	μΑ	I _F =Rated I _{FT} V _{DRM} =Rated V _{DRM}

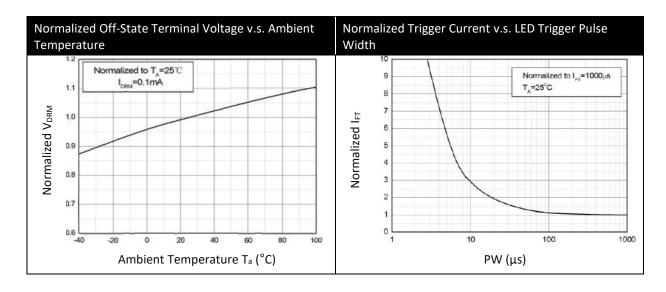
*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

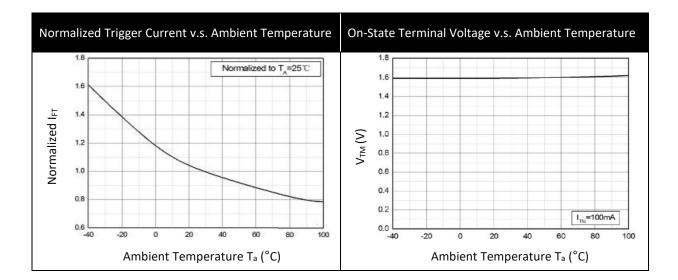


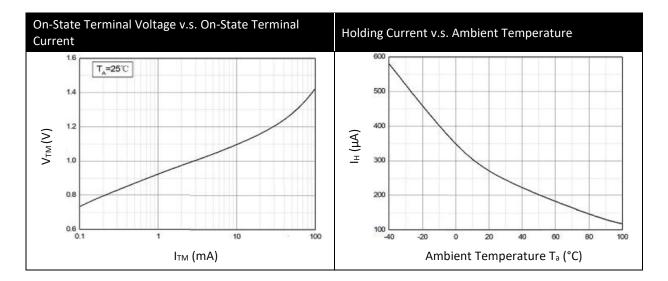


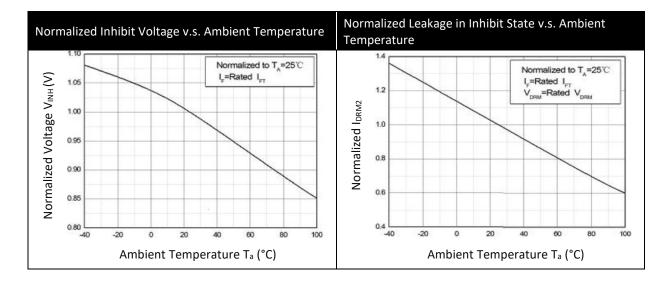




CHARACTERISTIC CURVES:

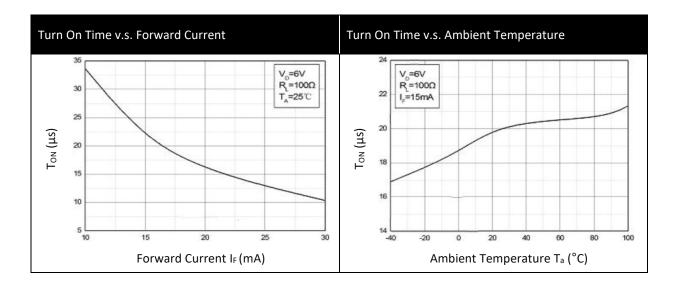






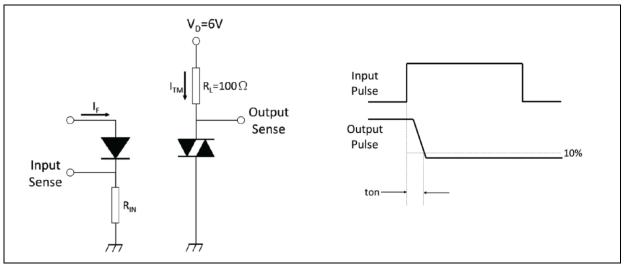


CHARACTERISTIC CURVES:



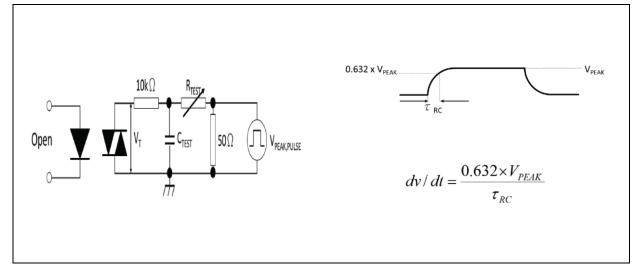


TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

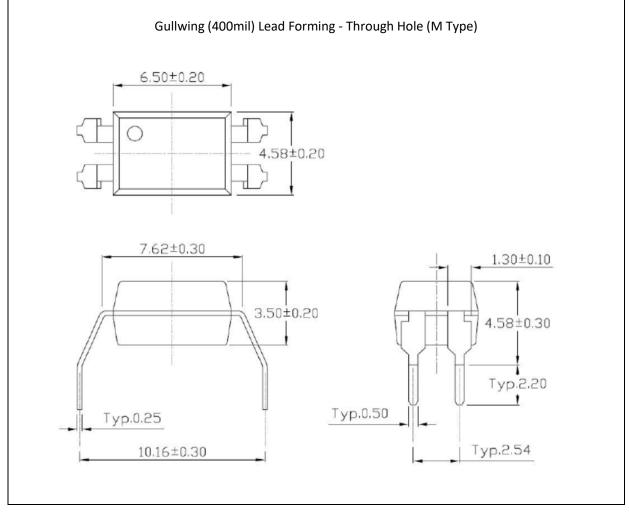
Test Circuit and Waveforms of dV/dt:





OUTLINE DIMENSION:

Package Dimension:

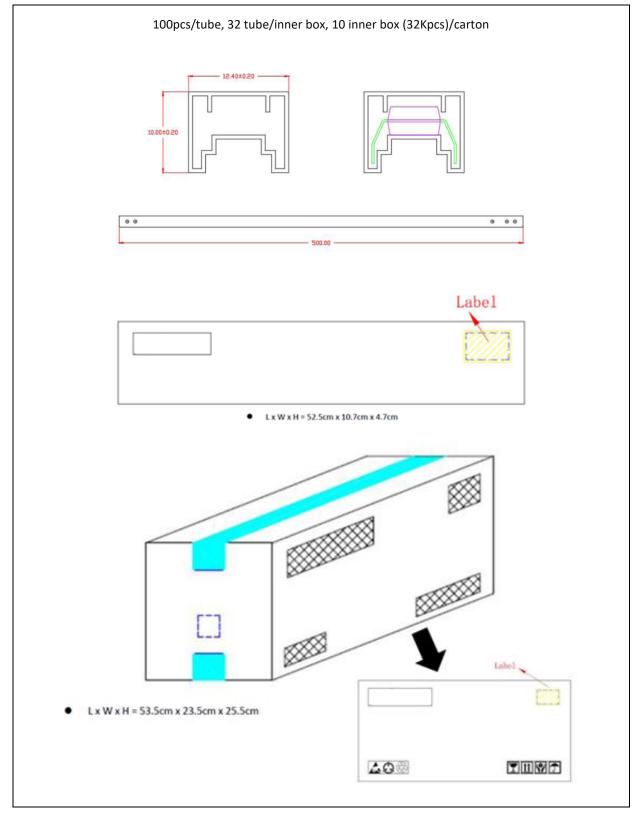


1. All dimensions are in millimetre (mm).



PACKING SPECIFICATION:

Tube Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

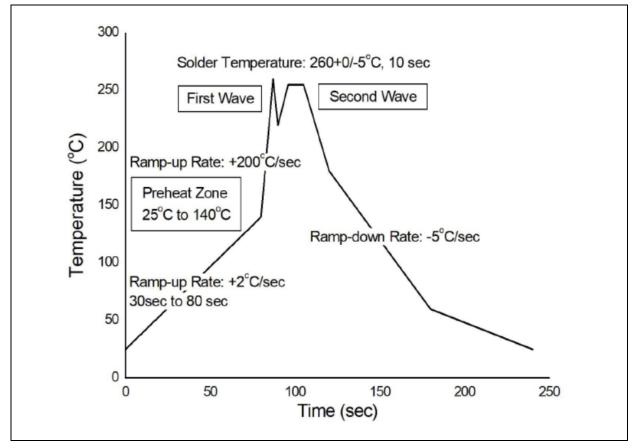
Г

Supplier $T_p \ge$	T_c Us T_c T_c T	er $T_p \leq T_c$
	,	t _p → T _c -5°C
1110 20 0 1		1
	Time ⇔	Pb-Free Assembly Profile
Profile Feature		Pb-Free Assembly Profile 150°C
Profile Feature Temperature Min. (T _{smin})	Time → Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Profile Feature	Time → Sn-Pb Assembly Profile 100°C	Pb-Free Assembly Profile 150°C
Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C	Pb-Free Assembly Profile 150°C 200°C
Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max.	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max.
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tt to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)Peak Body Package Temperature	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds 235°C +0°C / -5°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds 260°C +0°C / -5°C



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.